E·XFL

Intel - 10AS032E2F29E1HG Datasheet



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Embedded - System On Chip (SoC): The Heart of Modern Embedded Systems

Embedded - System On Chip (SoC) refers to an integrated circuit that consolidates all the essential components of a computer system into a single chip. This includes a microprocessor, memory, and other peripherals, all packed into one compact and efficient package. SoCs are designed to provide a complete computing solution, optimizing both space and power consumption, making them ideal for a wide range of embedded applications.

What are Embedded - System On Chip (SoC)?

System On Chip (SoC) integrates multiple functions of a computer or electronic system onto a single chip. Unlike traditional multi-chip solutions. SoCs combine a central

Details

Product Status	Active
Architecture	MCU, FPGA
Core Processor	Dual ARM® Cortex®-A9 MPCore [™] with CoreSight [™]
Flash Size	-
RAM Size	256KB
Peripherals	DMA, POR, WDT
Connectivity	EBI/EMI, Ethernet, I ² C, MMC/SD/SDIO, SPI, UART/USART, USB OTG
Speed	1.5GHz
Primary Attributes	FPGA - 320K Logic Elements
Operating Temperature	0°C ~ 100°C (TJ)
Package / Case	780-BBGA, FCBGA
Supplier Device Package	780-FBGA, FC (29x29)
Purchase URL	https://www.e-xfl.com/product-detail/intel/10as032e2f29e1hg

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong





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Key Advantages of Intel Arria 10 Devices

Table 2. Key Advantages of the Intel Arria 10 Device Family

Advantage	Supporting Feature
Enhanced core architecture	 Built on TSMC's 20 nm process technology 60% higher performance than the previous generation of mid-range FPGAs 15% higher performance than the fastest previous-generation FPGA
High-bandwidth integrated transceivers	 Short-reach rates up to 25.8 Gigabits per second (Gbps) Backplane capability up to 12.5 Gbps Integrated 10GBASE-KR and 40GBASE-KR4 Forward Error Correction (FEC)
Improved logic integration and hard IP blocks	 8-input adaptive logic module (ALM) Up to 65.6 megabits (Mb) of embedded memory Variable-precision digital signal processing (DSP) blocks Fractional synthesis phase-locked loops (PLLs) Hard PCI Express Gen3 IP blocks Hard memory controllers and PHY up to 2,400 Megabits per second (Mbps)
Second generation hard processor system (HPS) with integrated ARM* Cortex*-A9* MPCore* processor	 Tight integration of a dual-core ARM Cortex-A9 MPCore processor, hard IP, and an FPGA in a single Intel Arria 10 system-on-a-chip (SoC) Supports over 128 Gbps peak bandwidth with integrated data coherency between the processor and the FPGA fabric
Advanced power savings	 Comprehensive set of advanced power saving features Power-optimized MultiTrack routing and core architecture Up to 40% lower power compared to previous generation of mid-range FPGAs Up to 60% lower power compared to previous generation of high-end FPGAs

Summary of Intel Arria 10 Features

Table 3. Summary of Features for Intel Arria 10 Devices

Feature	Description
Technology	 TSMC's 20-nm SoC process technology Allows operation at a lower V_{CC} level of 0.82 V instead of the 0.9 V standard V_{CC} core voltage
Packaging	 1.0 mm ball-pitch Fineline BGA packaging 0.8 mm ball-pitch Ultra Fineline BGA packaging Multiple devices with identical package footprints for seamless migration between different FPGA densities Devices with compatible package footprints allow migration to next generation high-end Stratix[®] 10 devices RoHS, leaded⁽¹⁾, and lead-free (Pb-free) options
High-performance FPGA fabric	 Enhanced 8-input ALM with four registers Improved multi-track routing architecture to reduce congestion and improve compilation time Hierarchical core clocking architecture Fine-grained partial reconfiguration
Internal memory blocks	 M20K—20-Kb memory blocks with hard error correction code (ECC) Memory logic array block (MLAB)—640-bit memory
	continued

⁽¹⁾ Contact Intel for availability.



Feature	Description	
Low-power serial transceivers	 Continuous operating range: Intel Arria 10 GX—1 Gbps to 17.4 Gbps Intel Arria 10 GT—1 Gbps to 25.8 Gbps Backplane support: Intel Arria 10 GX—up to 12.5 Intel Arria 10 GT—up to 12.5 Extended range down to 125 Mbps with oversampling ATX transmit PLLs with user-configurable fractional synthesis capability Electronic Dispersion Compensation (EDC) support for XFP, SFP+, QSFP, and CFP optical module Adaptive linear and decision feedback equalization Transmitter pre-emphasis and de-emphasis Dynamic partial reconfiguration of individual transceiver channels 	
HPS (Intel Arria 10 SX devices only)	Processor and system • Dual-core ARM Cortex-A9 MPCore processor—1.2 GHz CPU with 1.5 GHz overdrive capability • 256 KB on-chip RAM and 64 KB on-chip ROM • System peripherals—general-purpose timers, watchdog timers, di memory access (DMA) controller, FPGA configuration manager, ar clock and reset managers • Security features—anti-tamper, secure boot, Advanced Encryptior Standard (AES) and authentication (SHA) • ARM CoreSight* JTAG debug access port, trace port, and on-chip trace storage	nd n
	 External interfaces Hard memory interface—Hard memory controller (2,400 Mbps DE and 2,133 Mbps DDR3), Quad serial peripheral interface (QSPI) fl controller, NAND flash controller, direct memory access (DMA) controller, Secure Digital/MultiMediaCard (SD/MMC) controller Communication interface—10/100/1000 Ethernet media access control (MAC), USB On-The-GO (OTG) controllers, I²C controllers, UART 16550, serial peripheral interface (SPI), and up to 62 HPS GPIO interfaces (48 direct-share I/Os) 	lash
	Interconnects to core • High-performance ARM AMBA* AXI bus bridges that support simultaneous read and write • HPS-FPGA bridges—include the FPGA-to-HPS, HPS-to-FPGA, and lightweight HPS-to-FPGA bridges that allow the FPGA fabric to iss transactions to slaves in the HPS, and vice versa • Configuration bridge that allows HPS configuration manager to configure the core logic via dedicated 32-bit configuration port • FPGA-to-HPS SDRAM controller bridge—provides configuration interfaces for the multiport front end (MPFE) of the HPS SDRAM controller	
Configuration	 Tamper protection—comprehensive design protection to protect your valuable IP investment Enhanced 256-bit advanced encryption standard (AES) design security with authentication Configuration via protocol (CvP) using PCIe Gen1, Gen2, or Gen3 	
	continue	d

 $^{^{(2)}\,}$ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Maximum Resources

Table 5.Maximum Resource Counts for Intel Arria 10 GX Devices (GX 160, GX 220, GX
270, GX 320, and GX 480)

Reso	ource			Product Line			
		GX 160	GX 220	GX 270	GX 320	GX 480	
Logic Elements	Logic Elements (LE) (K)		220	270	320	480	
ALM		61,510	80,330	101,620	119,900	183,590	
Register		246,040	321,320	406,480	479,600	734,360	
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	
	MLAB	1,050	1,690	2,452	2,727	4,164	
Variable-precisi	on DSP Block	156	192	192 830 985		1,368	
18 x 19 Multipli	er	312	384	1,660	1,970	2,736	
PLL	Fractional Synthesis	6	6	8	8	12	
	I/O	6	6	8	8	12	
17.4 Gbps Trans	sceiver	12	12	24	24	36	
GPIO ⁽³⁾		288	288	384	384	492	
LVDS Pair ⁽⁴⁾		120	120	168	168	222	
PCIe Hard IP Bl	ock	1	1	2	2	2	
Hard Memory C	ontroller	6	6	8	8	12	

⁽³⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁴⁾ Each LVDS I/O pair can be used as differential input or output.



Table 6.Maximum Resource Counts for Intel Arria 10 GX Devices (GX 570, GX 660, GX 900, and GX 1150)

Re	source		Produc	t Line		
		GX 570	GX 660	GX 900	GX 1150	
Logic Elements	s (LE) (K)	570	660	900	1,150	
ALM		217,080	251,680	339,620 427,20		
Register		868,320	1,006,720	1,358,480	1,708,800	
Memory (Kb)	M20K	36,000	42,620	48,460	54,260	
	MLAB	5,096	5,788	9,386	12,984	
Variable-precis	sion DSP Block	1,523	1,687	1,518 1,518		
18 x 19 Multip	lier	3,046	3,374	3,036	3,036	
PLL	Fractional Synthesis	16	16	32	32	
	I/O	16	16	16	16	
17.4 Gbps Trai	nsceiver	48	48	96	96	
GPIO ⁽³⁾		696	696	768	768	
LVDS Pair ⁽⁴⁾	LVDS Pair ⁽⁴⁾		324	384	384	
PCIe Hard IP E	Block	2	2	4	4	
Hard Memory	Controller	16	16	16	16	

Package Plan

Table 7.Package Plan for Intel Arria 10 GX Devices (U19, F27, and F29)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)				F27 mm × 27 n 72-pin FBG/		F29 (29 mm × 29 mm, 780-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	
GX 160	48	192	6	48	192	12	48	240	12	
GX 220	48	192	6	48	192	12	48	240	12	
GX 270	-	-	_	48	192	12	48	312	12	
GX 320	-	-	_	48	192	12	48	312	12	
GX 480	_	_	_	_	_	_	48	312	12	



Table 8. Package Plan for Intel Arria 10 GX Devices (F34, F35, NF40, and KF40)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	F34 (35 mm × 35 mm, 1152-pin FBGA)			F35 (35 mm × 35 mm, 1152-pin FBGA)			KF40 (40 mm × 40 mm, 1517-pin FBGA)			NF40 (40 mm × 40 mm, 1517-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
GX 270	48	336	24	48	336	24	_	_	_	_	-	-
GX 320	48	336	24	48	336	24	_	-	_	_	-	-
GX 480	48	444	24	48	348	36	_	-	-	_	-	-
GX 570	48	444	24	48	348	36	96	600	36	48	540	48
GX 660	48	444	24	48	348	36	96	600	36	48	540	48
GX 900	-	504	24	-	-	-	_	-	-	_	600	48
GX 1150	-	504	24	-	-	-	_	-	-	_	600	48

Table 9. Package Plan for Intel Arria 10 GX Devices (RF40, NF45, SF45, and UF45)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	RF40 (40 mm × 40 mm, 1517-pin FBGA)			NF45 (45 mm × 45 mm) 1932-pin FBGA)			SF45 (45 mm × 45 mm) 1932-pin FBGA)			UF45 (45 mm × 45 mm) 1932-pin FBGA)		
	3 V I/O	LVDS I/O	XCVR									
GX 900	_	342	66	_	768	48	_	624	72	_	480	96
GX 1150	_	342	66	_	768	48	_	624	72	_	480	96

Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 GT

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 GT devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.



Related Information

I/O and High-Speed Differential I/O Interfaces in Intel Arria 10 Devices chapter, Intel Arria 10 Device Handbook

Provides the number of 3 V and LVDS I/Os, and LVDS channels for each Intel Arria 10 device package.

Intel Arria 10 SX

This section provides the available options, maximum resource counts, and package plan for the Intel Arria 10 SX devices.

The information in this section is correct at the time of publication. For the latest information and to get more details, refer to the Intel FPGA Product Selector.

Related Information

Intel FPGA Product Selector

Provides the latest information on Intel products.

Available Options

Figure 3. Sample Ordering Code and Available Options for Intel Arria 10 SX Devices



Related Information

Transceiver Performance for Intel Arria 10 GX/SX Devices Provides more information about the transceiver speed grade.



Maximum Resources

Table 12. Maximum Resource Counts for Intel Arria 10 SX Devices

Reso	ource			I	Product Line			
		SX 160	SX 220	SX 270	SX 320	SX 480	SX 570	SX 660
Logic Elements (LE) (K)		160	220	270	320	480	570	660
ALM		61,510	80,330	101,620	119,900	183,590	217,080	251,680
Register		246,040	321,320	406,480	479,600	734,360	868,320	1,006,720
Memory (Kb)	M20K	8,800	11,740	15,000	17,820	28,620	36,000	42,620
	MLAB	1,050	1,690	2,452	2,727	4,164	5,096	5,788
Variable-precision DSP Block		156	192	830	985	1,368	1,523	1,687
18 x 19 Multiplier		312	384	1,660	1,970	2,736	3,046	3,374
PLL	Fractional Synthesis	6	6	8	8	12	16	16
	I/O	6	6	8	8	12	16	16
17.4 Gbps Tra	nsceiver	12	12	24	24	36	48	48
GPIO ⁽⁸⁾		288	288	384	384	492	696	696
LVDS Pair ⁽⁹⁾		120	120	168	168	174	324	324
PCIe Hard IP Block		1	1	2	2	2	2	2
Hard Memory Controller		6	6	8	8	12	16	16
ARM Cortex-A9 MPCore Processor		Yes	Yes	Yes	Yes	Yes	Yes	Yes

Package Plan

Table 13.Package Plan for Intel Arria 10 SX Devices (U19, F27, F29, and F34)

Refer to I/O and High Speed I/O in Intel Arria 10 Devices chapter for the number of 3 V I/O, LVDS I/O, and LVDS channels in each device package.

Product Line	U19 (19 mm × 19 mm, 484-pin UBGA)		F27 (27 mm × 27 mm, 672-pin FBGA)			F29 (29 mm × 29 mm, 780-pin FBGA)			F34 (35 mm × 35 mm, 1152-pin FBGA)			
	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR	3 V I/O	LVDS I/O	XCVR
SX 160	48	144	6	48	192	12	48	240	12	_	-	-
SX 220	48	144	6	48	192	12	48	240	12	_	-	-
SX 270	-	-	_	48	192	12	48	312	12	48	336	24
SX 320	-			48	192	12	48	312	12	48	336	24
			continued									

⁽⁸⁾ The number of GPIOs does not include transceiver I/Os. In the Intel Quartus Prime software, the number of user I/Os includes transceiver I/Os.

⁽⁹⁾ Each LVDS I/O pair can be used as differential input or output.



I/O Vertical Migration for Intel Arria 10 Devices

Figure 4. Migration Capability Across Intel Arria 10 Product Lines

- The arrows indicate the migration paths. The devices included in each vertical migration path are shaded. Devices with fewer resources in the same path have lighter shades.
- To achieve the full I/O migration across product lines in the same migration path, restrict I/Os and transceivers usage to match the product line with the lowest I/O and transceiver counts.
- An LVDS I/O bank in the source device may be mapped to a 3 V I/O bank in the target device. To use
 memory interface clock frequency higher than 533 MHz, assign external memory interface pins only to
 banks that are LVDS I/O in both devices.
- There may be nominal 0.15 mm package height difference between some product lines in the same package type.
 - Package Product Variant Line U19 F27 KF40 NF40 RF40 NF45 SF45 UF45 F29 F34 F35 GX 160 GX 220 GX 270 GX 320 Intel® Arria® 10 GX GX 480 GX 570 GX 660 GX 900 GX 1150 GT 900 Intel Arria 10 GT GT 1150 SX 160 SX 220 SX 270 Intel Arria 10 SX SX 320 SX 480 SX 570 SX 660
- Some migration paths are not shown in the Intel Quartus Prime software Pin Migration View.

Note: To verify the pin migration compatibility, use the **Pin Migration View** window in the Intel Quartus Prime software Pin Planner.

Adaptive Logic Module

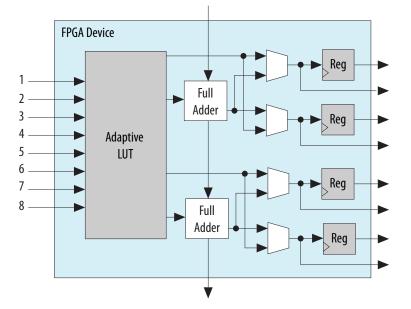
Intel Arria 10 devices use a 20 nm ALM as the basic building block of the logic fabric.

The ALM architecture is the same as the previous generation FPGAs, allowing for efficient implementation of logic functions and easy conversion of IP between the device generations.

The ALM, as shown in following figure, uses an 8-input fracturable look-up table (LUT) with four dedicated registers to help improve timing closure in register-rich designs and achieve an even higher design packing capability than the traditional two-register per LUT architecture.



Figure 5. ALM for Intel Arria 10 Devices



The Intel Quartus Prime software optimizes your design according to the ALM logic structure and automatically maps legacy designs into the Intel Arria 10 ALM architecture.

Variable-Precision DSP Block

The Intel Arria 10 variable precision DSP blocks support fixed-point arithmetic and floating-point arithmetic.

Features for fixed-point arithmetic:

- High-performance, power-optimized, and fully registered multiplication operations
- 18-bit and 27-bit word lengths
- Two 18 x 19 multipliers or one 27 x 27 multiplier per DSP block
- Built-in addition, subtraction, and 64-bit double accumulation register to combine multiplication results
- Cascading 19-bit or 27-bit when pre-adder is disabled and cascading 18-bit when pre-adder is used to form the tap-delay line for filtering applications
- Cascading 64-bit output bus to propagate output results from one block to the next block without external logic support
- Hard pre-adder supported in 19-bit and 27-bit modes for symmetric filters
- Internal coefficient register bank in both 18-bit and 27-bit modes for filter implementation
- 18-bit and 27-bit systolic finite impulse response (FIR) filters with distributed output adder
- Biased rounding support



Features for floating-point arithmetic:

- A completely hardened architecture that supports multiplication, addition, subtraction, multiply-add, and multiply-subtract
- Multiplication with accumulation capability and a dynamic accumulator reset control
- Multiplication with cascade summation capability
- Multiplication with cascade subtraction capability
- Complex multiplication
- Direct vector dot product
- Systolic FIR filter

Table 15. Variable-Precision DSP Block Configurations for Intel Arria 10 Devices

Usage Example	Multiplier Size (Bit)	DSP Block Resources
Medium precision fixed point	Two 18 x 19	1
High precision fixed or Single precision floating point	One 27 x 27	1
Fixed point FFTs	One 19 x 36 with external adder	1
Very high precision fixed point	One 36 x 36 with external adder	2
Double precision floating point	One 54 x 54 with external adder	4

Table 16. Resources for Fixed-Point Arithmetic in Intel Arria 10 Devices

The table lists the variable-precision DSP resources by bit precision for each Intel Arria 10 device.

Variant	Product Line	Variable- precision DSP Block	Independent Input and Output Multiplications Operator		18 x 19 Multiplier Adder Sum	18 x 18 Multiplier Adder	
		DSP BIOCK	18 x 19 Multiplier	27 x 27 Multiplier	Mode	Summed with 36 bit Input	
AIntel Arria 10 GX	GX 160	156	312	156	156	156	
GX	GX 220	192	384	192	192	192	
	GX 270	830	1,660	830	830	830	
	GX 320	984	1,968	984	984	984	
	GX 480	1,368	2,736	1,368	1,368	1,368	
	GX 570	1,523	3,046	1,523	1,523	1,523	
	GX 660	1,687	3,374	1,687	1,687	1,687	
	GX 900	1,518	3,036	1,518	1,518	1,518	
	GX 1150	1,518	3,036	1,518	1,518	1,518	
Intel Arria 10	GT 900	1,518	3,036	1,518	1,518	1,518	
GT	GT 1150	1,518	3,036	1,518	1,518	1,518	
Intel Arria 10	SX 160	156	312	156	156	156	
SX	SX 220	192	384	192	192	192	
	SX 270	830	1,660	830	830	830	
						continued	



The fractional synthesis PLLs support the following features:

- Reference clock frequency synthesis for transceiver CMU and Advanced Transmit (ATX) PLLs
- Clock network delay compensation
- Zero-delay buffering
- Direct transmit clocking for transceivers
- Independently configurable into two modes:
 - Conventional integer mode equivalent to the general purpose PLL
 - Enhanced fractional mode with third order delta-sigma modulation
- PLL cascading

I/O PLLs

The integer mode I/O PLLs are located in each bank of 48 I/Os. You can use the I/O PLLs to simplify the design of external memory and high-speed LVDS interfaces.

In each I/O bank, the I/O PLLs are adjacent to the hard memory controllers and LVDS SERDES. Because these PLLs are tightly coupled with the I/Os that need to use them, it makes it easier to close timing.

You can use the I/O PLLs for general purpose applications in the core such as clock network delay compensation and zero-delay buffering.

Intel Arria 10 devices support PLL-to-PLL cascading.

FPGA General Purpose I/O

Intel Arria 10 devices offer highly configurable GPIOs. Each I/O bank contains 48 general purpose I/Os and a high-efficiency hard memory controller.

The following list describes the features of the GPIOs:

- Consist of 3 V I/Os for high-voltage application and LVDS I/Os for differential signaling
 - $-\,$ Up to two 3 V I/O banks, available in some devices, that support up to 3 V I/O standards
 - LVDS I/O banks that support up to 1.8 V I/O standards
- Support a wide range of single-ended and differential I/O interfaces
- LVDS speeds up to 1.6 Gbps
- Each LVDS pair of pins has differential input and output buffers, allowing you to configure the LVDS direction for each pair.
- Programmable bus hold and weak pull-up
- Programmable differential output voltage (V_{OD}) and programmable pre-emphasis



Table 20. Memory Standards Supported by the Hard Memory Controller

This table lists the overall capability of the hard memory controller. For specific details, refer to the External Memory Interface Spec Estimator and Intel Arria 10 Device Datasheet.

Memory Standard	Rate Support	Ping Pong PHY Support	Maximum Frequency (MHz)
DDR4 SDRAM	Quarter rate	Yes	1,067
		_	1,200
DDR3 SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	1,067
		_	1,067
DDR3L SDRAM	Half rate	Yes	533
		_	667
	Quarter rate	Yes	933
		_	933
LPDDR3 SDRAM	Half rate	-	533
	Quarter rate	_	800

Table 21. Memory Standards Supported by the Soft Memory Controller

Memory Standard	Rate Support	Maximum Frequency (MHz)
RLDRAM 3 (11)	Quarter rate	1,200
QDR IV SRAM ⁽¹¹⁾	Quarter rate	1,067
QDR II SRAM	Full rate	333
	Half rate	633
QDR II+ SRAM	Full rate	333
	Half rate	633
QDR II+ Xtreme SRAM	Full rate	333
	Half rate	633

Table 22. Memory Standards Supported by the HPS Hard Memory Controller

The hard processor system (HPS) is available in Intel Arria 10 SoC devices only.

Memory Standard	Rate Support	Maximum Frequency (MHz)
DDR4 SDRAM	Half rate	1,200
DDR3 SDRAM	Half rate	1,067
DDR3L SDRAM	Half rate	933

⁽¹¹⁾ Intel Arria 10 devices support this external memory interface using hard PHY with soft memory controller.



Related Information

Intel Arria 10 Device Datasheet

Lists the memory interface performance according to memory interface standards, rank or chip select configurations, and Intel Arria 10 device speed grades.

PCIe Gen1, Gen2, and Gen3 Hard IP

Intel Arria 10 devices contain PCIe hard IP that is designed for performance and ease-of-use:

- Includes all layers of the PCIe stack—transaction, data link and physical layers.
- Supports PCIe Gen3, Gen2, and Gen1 Endpoint and Root Port in x1, x2, x4, or x8 lane configuration.
- Operates independently from the core logic—optional configuration via protocol (CvP) allows the PCIe link to power up and complete link training in less than 100 ms while the Intel Arria 10 device completes loading the programming file for the rest of the FPGA.
- Provides added functionality that makes it easier to support emerging features such as Single Root I/O Virtualization (SR-IOV) and optional protocol extensions.
- Provides improved end-to-end datapath protection using ECC.
- Supports FPGA configuration via protocol (CvP) using PCIe at Gen3, Gen2, or Gen1 speed.

Related Information

PCS Features on page 30

Enhanced PCS Hard IP for Interlaken and 10 Gbps Ethernet

Interlaken Support

The Intel Arria 10 enhanced PCS hard IP provides integrated Interlaken PCS supporting rates up to 25.8 Gbps per lane.

The Interlaken PCS is based on the proven functionality of the PCS developed for Intel's previous generation FPGAs, which demonstrated interoperability with Interlaken ASSP vendors and third-party IP suppliers. The Interlaken PCS is present in every transceiver channel in Intel Arria 10 devices.

Related Information

PCS Features on page 30

10 Gbps Ethernet Support

The Intel Arria 10 enhanced PCS hard IP supports 10GBASE-R PCS compliant with IEEE 802.3 10 Gbps Ethernet (10GbE). The integrated hard IP support for 10GbE and the 10 Gbps transceivers save external PHY cost, board space, and system power.



The scalable hard IP supports multiple independent 10GbE ports while using a single PLL for all the 10GBASE-R PCS instantiations, which saves on core logic resources and clock networks:

- Simplifies multiport 10GbE systems compared to XAUI interfaces that require an external XAUI-to-10G PHY.
- Incorporates Electronic Dispersion Compensation (EDC), which enables direct connection to standard 10 Gbps XFP and SFP+ pluggable optical modules.
- Supports backplane Ethernet applications and includes a hard 10GBASE-KR Forward Error Correction (FEC) circuit that you can use for 10 Gbps and 40 Gbps applications.

The 10 Gbps Ethernet PCS hard IP and 10GBASE-KR FEC are present in every transceiver channel.

Related Information

PCS Features on page 30

Low Power Serial Transceivers

Intel Arria 10 FPGAs and SoCs include lowest power transceivers that deliver high bandwidth, throughput and low latency.

Intel Arria 10 devices deliver the industry's lowest power consumption per transceiver channel:

- 12.5 Gbps transceivers at as low as 242 mW
- 10 Gbps transceivers at as low as 168 mW
- 6 Gbps transceivers at as low as 117 mW

Intel Arria 10 transceivers support various data rates according to application:

- Chip-to-chip and chip-to-module applications—from 1 Gbps up to 25.8 Gbps
- Long reach and backplane applications—from 1 Gbps up to 12.5 with advanced adaptive equalization
- Critical power sensitive applications—from 1 Gbps up to 11.3 Gbps using lower power modes

The combination of 20 nm process technology and architectural advances provide the following benefits:

- Significant reduction in die area and power consumption
- Increase of up to two times in transceiver I/O density compared to previous generation devices while maintaining optimal signal integrity
- Up to 72 total transceiver channels—you can configure up to 6 of these channels to run as fast as 25.8 Gbps
- All channels feature continuous data rate support up to the maximum rated speed



Figure 7. Device Chip Overview for Intel Arria 10 GX and GT Devices



Figure 8. Device Chip Overview for Intel Arria 10 SX Devices



PMA Features

Intel Arria 10 transceivers provide exceptional signal integrity at data rates up to 25.8 Gbps. Clocking options include ultra-low jitter ATX PLLs (LC tank based), clock multiplier unit (CMU) PLLs, and fractional PLLs.



PCS	Description
Standard PCS	 Operates at a data rate up to 12 Gbps Supports protocols such as PCI-Express, CPRI 4.2+, GigE, IEEE 1588 in Hard PCS Implements other protocols using Basic/Custom (Standard PCS) transceiver configuration rules.
Enhanced PCS	 Performs functions common to most serial data industry standards, such as word alignment, encoding/decoding, and framing, before data is sent or received off-chip through the PMA Handles data transfer to and from the FPGA fabric Handles data transfer internally to and from the PMA Provides frequency compensation Performs channel bonding for multi-channel low skew applications
PCIe Gen3 PCS	 Supports the seamless switching of Data and Clock between the Gen1, Gen2, and Gen3 data rates Provides support for PIPE 3.0 features Supports the PIPE interface with the Hard IP enabled, as well as with the Hard IP bypassed

Related Information

- PCIe Gen1, Gen2, and Gen3 Hard IP on page 26
- Interlaken Support on page 26
- 10 Gbps Ethernet Support on page 26

PCS Protocol Support

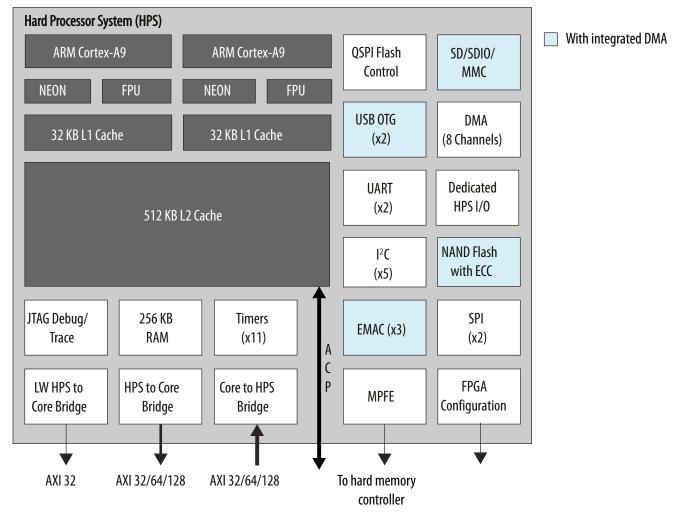
This table lists some of the protocols supported by the Intel Arria 10 transceiver PCS. For more information about the blocks in the transmitter and receiver data paths, refer to the related information.

Protocol	Data Rate (Gbps)	Transceiver IP	PCS Support
PCIe Gen3 x1, x2, x4, x8	8.0	Native PHY (PIPE)	Standard PCS and PCIe Gen3 PCS
PCIe Gen2 x1, x2, x4, x8	5.0	Native PHY (PIPE)	Standard PCS
PCIe Gen1 x1, x2, x4, x8	2.5	Native PHY (PIPE)	Standard PCS
1000BASE-X Gigabit Ethernet	1.25	Native PHY	Standard PCS
1000BASE-X Gigabit Ethernet with IEEE 1588v2	1.25	Native PHY	Standard PCS
10GBASE-R	10.3125	Native PHY	Enhanced PCS
10GBASE-R with IEEE 1588v2	10.3125	Native PHY	Enhanced PCS
10GBASE-R with KR FEC	10.3125	Native PHY	Enhanced PCS
10GBASE-KR and 1000BASE-X	10.3125	1G/10GbE and 10GBASE-KR PHY	Standard PCS and Enhanced PCS
Interlaken (CEI-6G/11G)	3.125 to 17.4	Native PHY	Enhanced PCS
SFI-S/SFI-5.2	11.2	Native PHY	Enhanced PCS
10G SDI	10.692	Native PHY	Enhanced PCS
			continued



Figure 9. HPS Block Diagram

This figure shows a block diagram of the HPS with the dual ARM Cortex-A9 MPCore processor.



Key Advantages of 20-nm HPS

The 20-nm HPS strikes a balance between enabling maximum software compatibility with 28-nm SoCs while still improving upon the 28-nm HPS architecture. These improvements address the requirements of the next generation target markets such as wireless and wireline communications, compute and storage equipment, broadcast and military in terms of performance, memory bandwidth, connectivity via backplane and security.



Features of the HPS

The HPS has the following features:

- 1.2-GHz, dual-core ARM Cortex-A9 MPCore processor with up to 1.5-GHz via overdrive
 - ARMv7-A architecture that runs 32-bit ARM instructions, 16-bit and 32-bit Thumb instructions, and 8-bit Java byte codes in Jazelle style
 - Superscalar, variable length, out-of-order pipeline with dynamic branch prediction
 - Instruction Efficiency 2.5 MIPS/MHz, which provides total performance of 7500 MIPS at 1.5 GHz
- Each processor core includes:
 - 32 KB of L1 instruction cache, 32 KB of L1 data cache
 - Single- and double-precision floating-point unit and NEON media engine
 - CoreSight debug and trace technology
 - Snoop Control Unit (SCU) and Acceleration Coherency Port (ACP)
- 512 KB of shared L2 cache
- 256 KB of scratch RAM
- Hard memory controller with support for DDR3, DDR4 and optional error correction code (ECC) support
- Multiport Front End (MPFE) Scheduler interface to the hard memory controller
- 8-channel direct memory access (DMA) controller
- QSPI flash controller with SIO, DIO, QIO SPI Flash support
- NAND flash controller (ONFI 1.0 or later) with DMA and ECC support, updated to support 8 and 16-bit Flash devices and new command DMA to offload CPU for fast power down recovery
- Updated SD/SDIO/MMC controller to eMMC 4.5 with DMA with CE-ATA digital command support
- 3 10/100/1000 Ethernet media access control (MAC) with DMA
- 2 USB On-the-Go (OTG) controllers with DMA
- 5 I²C controllers (3 can be used by EMAC for MIO to external PHY)
- 2 UART 16550 Compatible controllers
- 4 serial peripheral interfaces (SPI) (2 Master, 2 Slaves)
- 62 programmable general-purpose I/Os, which includes 48 direct share I/Os that allows the HPS peripherals to connect directly to the FPGA I/Os
- 7 general-purpose timers
- 4 watchdog timers
- Anti-tamper, Secure Boot, Encryption (AES) and Authentication (SHA)



Instead of placing all device functions in the FPGA fabric, you can store some functions that do not run simultaneously in external memory and load them only when required. This capability increases the effective logic density of the device, and lowers cost and power consumption.

In the Intel solution, you do not have to worry about intricate device architecture to perform a partial reconfiguration. The partial reconfiguration capability is built into the Intel Quartus Prime design software, making such time-intensive task simple.

Intel Arria 10 devices support partial reconfiguration in the following configuration options:

- Using an internal host:
 - All supported configuration modes where the FPGA has access to external memory devices such as serial and parallel flash memory.
 - Configuration via Protocol [CvP (PCIe)]
- Using an external host—passive serial (PS), fast passive parallel (FPP) x8, FPP x16, and FPP x32 I/O interface.

Enhanced Configuration and Configuration via Protocol

Table 25. Configuration Schemes and Features of Intel Arria 10 Devices

Intel Arria 10 devices support 1.8 V programming voltage and several configuration schemes.

Scheme	Data Width	Max Clock Rate (MHz)	Max Data Rate (Mbps) (13)	Decompression	Design Security ⁽¹ 4)	Partial Reconfiguration (15)	Remote System Update
JTAG	1 bit	33	33	_	-	Yes ⁽¹⁶⁾	-
Active Serial (AS) through the EPCQ-L configuration device	1 bit, 4 bits	100	400	Yes	Yes	Yes ⁽¹⁶⁾	Yes
Passive serial (PS) through CPLD or external microcontroller	1 bit	100	100	Yes	Yes	Yes ⁽¹⁶⁾	Parallel Flash Loader (PFL) IP core
	continued						

⁽¹³⁾ Enabling either compression or design security features affects the maximum data rate. Refer to the Intel Arria 10 Device Datasheet for more information.

⁽¹⁴⁾ Encryption and compression cannot be used simultaneously.

⁽¹⁵⁾ Partial reconfiguration is an advanced feature of the device family. If you are interested in using partial reconfiguration, contact Intel for support.

⁽¹⁶⁾ Partial configuration can be performed only when it is configured as internal host.